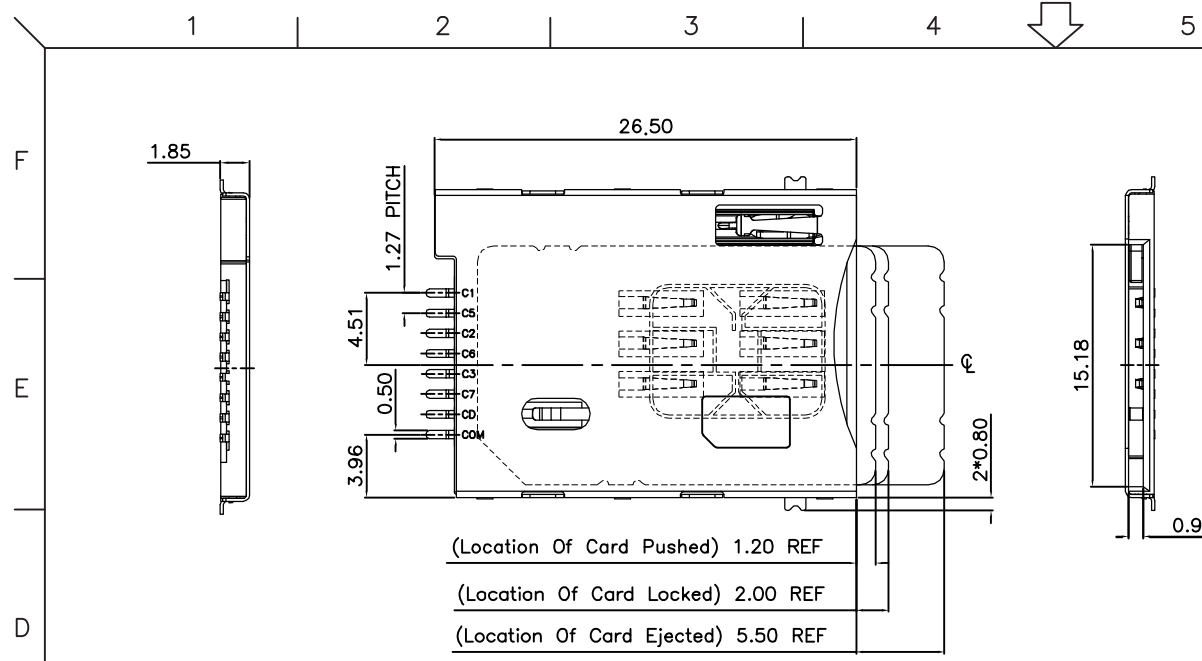
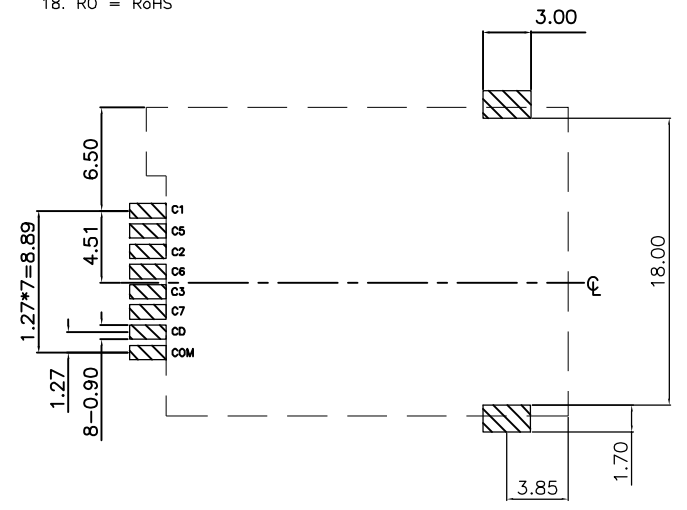
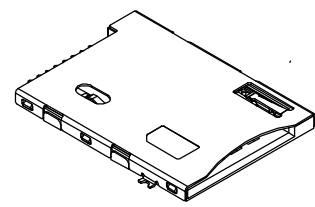
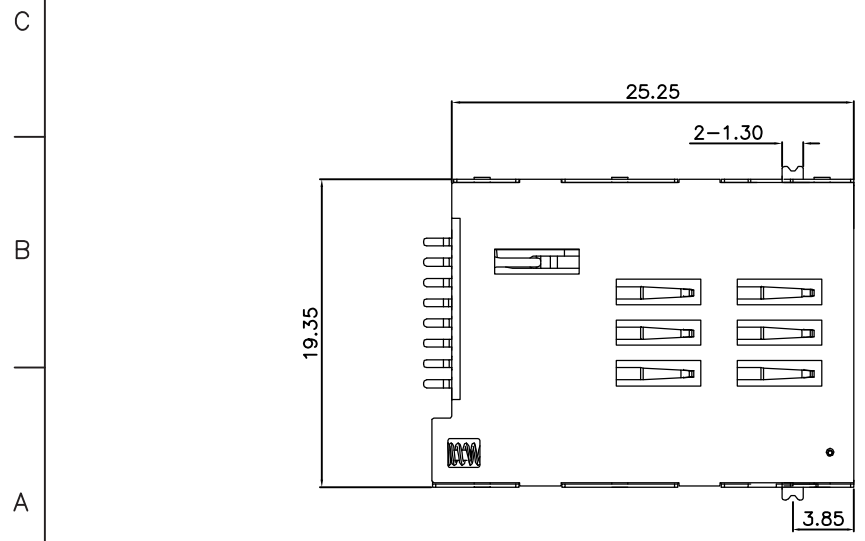
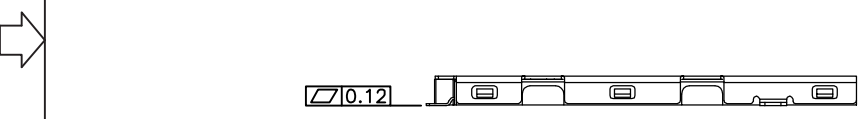


Rev.	Description	Date	Drawn	Checked
A	INITIAL RELEASE	2015.04.10	SWC	



Material and Finish:

1. Insulator Material: L.C.P+30% Glass Filled, UL94V-0 Color:Black
2. CMA Housing Material: Nylon-9T+30% Glass Filled, UL94V-0 Color:Black
3. Contact Material: Phosphor Bronze, C5191-EH, T=0.15
4. Terminal Material: Phosphor Bronze, C5191-EH, T=0.15
5. Contact Area Plated: 3u" Gold Plated Over 50u" Nickel
6. Solder Area Plated: 100u" Tin Plated Over 50u" Nickel
7. Wire Spring: SUS304-WPB, Nickel Plated
8. Shell Material: Stainless Steel SUS 301, T=0.2
9. Shell Solder Area plated: 2u" Selective Gold Plated For One Side
10. CAM Pin: SUS304-WPB, Nickel Plated
11. Current Rating: 0.5A AC/DC Max.
12. Contact Resistance: 100m ohms Max.
13. Insulation Resistance: 500m ohms Min.
14. Dielectric withstanding Voltage: 250V AC/DC
15. Insertion Cycles: 5,000 Cycles Min
16. Operation Teperature: -40°C to +85°C
17. Packing: Tape & Reel
18. RO = RoHS



Recommended PCB Layout

GENERAL TOLERANCE:
 .X ±0.30 Ang. ±2°
 .XX ±0.25
 .XXX ±0.15

Singatron Enterprise Co., Ltd.			
TITLE	SIM Card Connector 8 Pin, Push-Push Type, H: 1.85 mm		
DWN	SWC 2015.04	PART NO.	2SIMMP-10803B601
CHKD	SCALE 1:1	UNIT: mm	
APVD	SIZE: A3	SHEET: 1 OF 1	
CUSTOMER COPY			